



ESD SMD Comm COG, Ceramic, 0.01 uF, 2%, 63 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 1206, 1.5 mm



General Information	
Series	ESD SMD Comm COG
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	20 mg
Shelf Life	78 Weeks
MSL	1

0.01 uF

1 kHz 1.0Vrms

Dimensions	
Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
Т	0.9mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm

Т	0.9mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm
Packaging Specifications	

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	1.6mm +/-0.35mm	Tolerance	2%
	0.9mm +/-0.20mm	Voltage DC	63 VDC
	1.5mm MIN	ESD Level per AEC-Q200	25,000 V ESD Level
	0.6mm +/-0.25mm	Dielectric Withstanding Voltage	157.5 VDC
		Temperature Range	-55/+125°C
Specifications		Temp. Coefficient	COG
Quantity	Bulk, Bag 1	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
	Dissipation Factor	0.1% 1 kHz 1.0Vrms	
	Aging Rate	0% Loss/Decade Hour	

Specifications

Measurement Condition

Capacitance

30 ppm/C, 1kHz 1.0Vrms

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